

**FOR ADDITIONAL INFORMATION
CONTACT:**

Phone: (518) 452-2880
E-mail: info@yincae.com



YINCAE Advanced Materials, LLC
19 Walker Way, Albany, NY 12205
(518) 452-2880
www.yincae.com

FOR IMMEDIATE RELEASE

Press Release

YINCAE is Exhibiting at the Electronics Packaging Symposium

(Albany, NY) 8/9/2018 – YINCAE is excited to announce that we will be an exhibitor at the 30th Annual Binghamton University and GE Electronics Packaging Symposium this September 18-19th. The event will be held at the Binghamton University Innovative Technologies Complex in Binghamton, NY.

YINCAE Advanced Materials offers a wide range of materials used in electronics packaging, such as potting epoxy, conformal coatings, and die attach adhesives. We also offer several types of underfill including traditional capillary underfill as well as no flow underfill and highly thermally conductive underfill (including the only commercially available diamond filled underfill that has a thermal conductivity of 6W/mK). These materials, along with our solder joint encapsulant pastes (that can withstand up to 5x reflow, which makes them very useful for 3D applications) mean that YINCAE can provide all of the adhesives and coatings used during electronic manufacturing.

To schedule a meeting with the YINCAE team during the exhibition, please email us at: info@yincae.com with a brief description of the meeting topic. You can also find more information by visiting our website at: www.yincae.com

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

###

The YINCAE brand name and logo are trademarks of YINCAE Advanced Materials, LLC.